

1. A film deposition apparatus comprising:  
a container forming a processing chamber for processing a target object;  
a mounting table which is provided in the processing chamber and on which the target object is mounted;  
a first heating apparatus provided in the mounting table, for heating the target object mounted on the mounting table;  
a first gas supply section provided in the container, for supplying processing gas into the processing chamber, the processing gas forming a high-melting-point metal-film layer on the target object mounted on the mounting table;  
a movable clamp for clamping an edge portion of the target object and holding the target object on the mounting table;  
a second heating apparatus formed separately from the clamp, for heating the clamp indirectly;  
a gas flow path formed between the clamp and the second heating apparatus when the clamp is moved to a position where the clamp clamps the target object; and  
a second gas supply section for causing backside gas to flow into the gas flow path.

2. The film deposition apparatus according to claim 1, wherein the gas flow path extends so as to

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6. The film deposition apparatus according to

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9. The film deposition apparatus according to

claim 1, wherein the gas flow path is provided with a

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add  
a<sup>6</sup>  
c<sup>2</sup>